

taoglas

DSGP. 18.2.A

### DSGP.1575.18.2.A.02

#### **Description:**

GPS L1 / GALILEO E1 1575.42MHz 18\*18\*2mm Ceramic Patch SMD

#### Features:

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## 1. Introduction



The DSGP.1575.18.2.A.02 is a ceramic GPS L1 / GALILEO E1 passive patch antenna, 18mm square, with a low profile of 2mm thickness. It is designed for applications in space constrained navigation devices, vehicle tracking/fleet management systems, as well as telematics devices.

The antenna has been tuned on a 50 x 50 mm ground plane, working at 1575.42MHz with a 2.4 dBi gain. The ceramic patch is mounted via SMT process, ideal for high volume low cost assembly. It is manufactured and tested in a TS16949 first tier automotive approved facility.

For further optimization to customer specific device environments where ground-plane size is different, custom tuned patch antennas can be supplied. For more details please contact your regional Taoglas sales office.



## Specifications

GNSS Frequency Bands Covered							
GPS/QZSS	L1 1575.42MHz	L2 1227.6MHz	L5 1176.45MHz	L6 1278.75MHz			
GLONASS	L5R 1176.45MHz	L3PT 1201.5MHz	L2PT 1246MHz	L1CR 1575.42MHz	L1PT 1602MHz		
				V			
Galileo	E5a 1176.45MHz	E5b 1201.5MHz	E4 1215MHz	E3 1256MHz	E6 1278.75MHz	E2 1561MHz	L1 1575.42MHz
BeiDou	B1 1561MHz	B2 1207.14MHz	B3 1268.52MHz				
Compass	E5B(B2)/ E6(B3) 1268.56MHz	E2(B1) 1561MHz					
SBAS	Omnistar 1542.5MHz	WAAS/EGN OS 1575.42MHz					

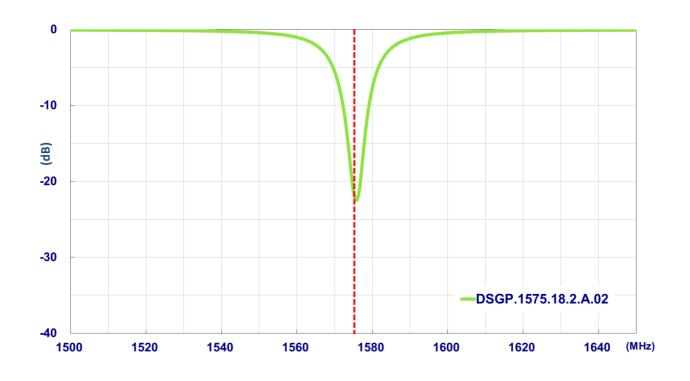


Electrical			
Frequency (MHz)	1575.42		
VSWR (max.)	2.0:1		
Passive Antenna Efficiency (%)	55.94		
Passive Antenna Gain at Zenith (dBi)	2.4		
Return Loss (dB)	<-10		
Impedance	50Ω		
Mechanical			
Dimensions	18 x18 x 2 mm		
Weight	3.3g		
Material	Ceramic		
Environmental			
Temperature Range	-40°C to 85°C		
Humidity	Non-condensing 65°C 95% RH		
Moisture Sensitivity Level (MSL)	3 (168 Hours)		

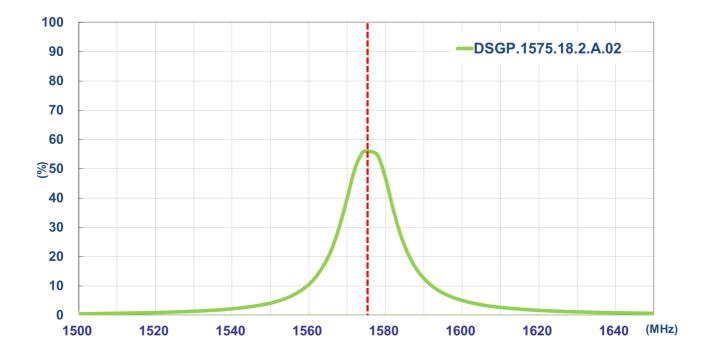








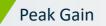
**3.2** Efficiency

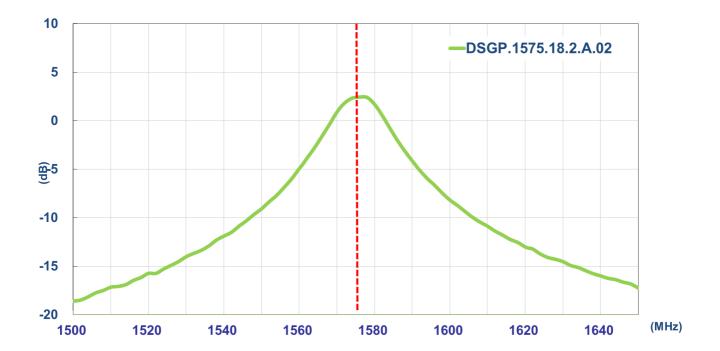










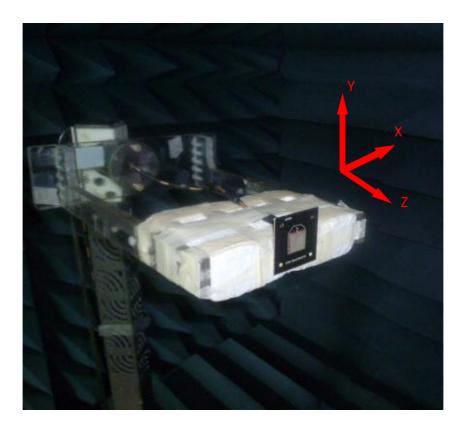




## Radiation Patterns



4.

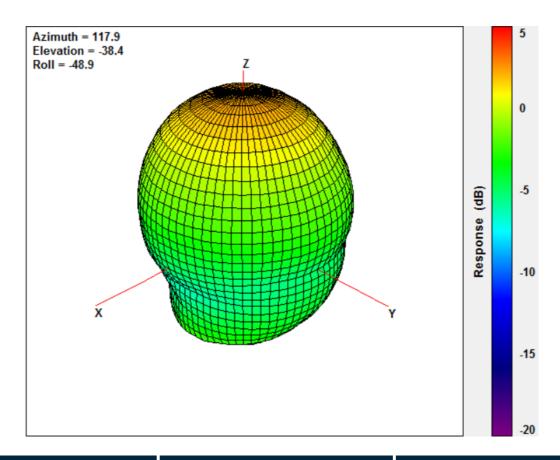


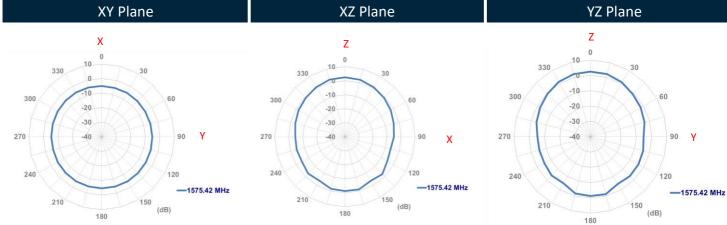
On Evaluation Board

Taoglas Part number: DSGPD.18B

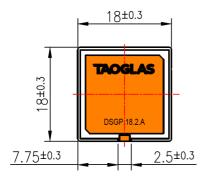


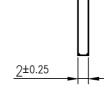
### 1575.42MHz 3D and 2D Radiation Patterns

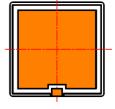










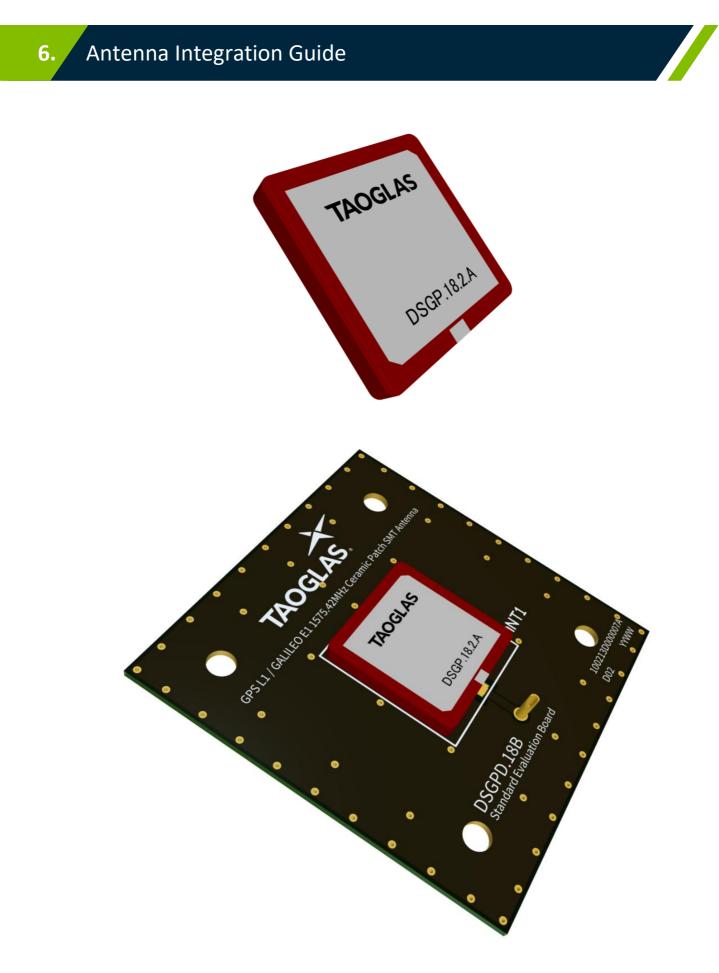


Top View

Side View

**Bottom View** 



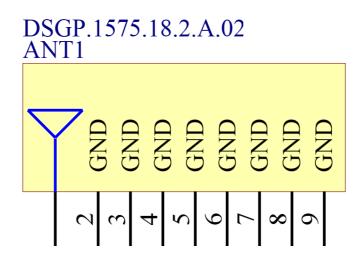




### 6.1 Schematic Symbol and Pin Definition

The circuit symbol for the antenna is shown below. The antenna has 8 pins with all as functional.

Pin	Description
1	RF Feed
2, 3, 4, 5, 6, 7, 8	Ground



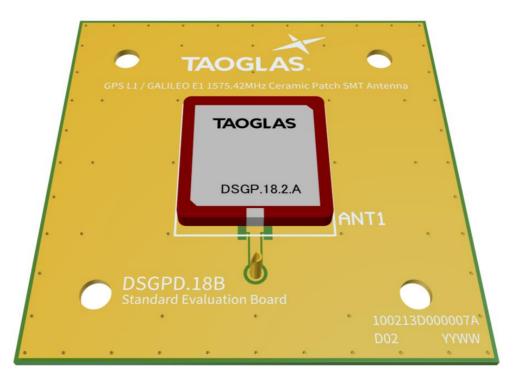


### 6.2 Antenna Integration

The antenna should be placed at the center of the ground plane with a length and width of 50mm. Maintaining a square symmetric ground plane shape and symmetric environment around the antenna is critical to maintaining the excellent axial ratio and phase center performance shown in this datasheet.



Top Side w/ Solder Mask



Top Side w/o Solder Mask

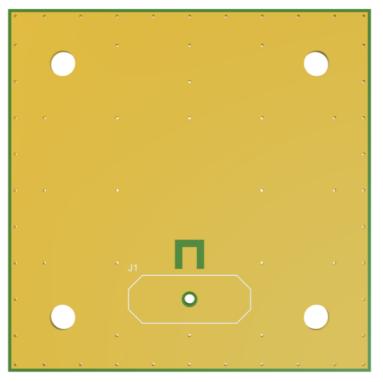


### 6.3 PCB Layout

The footprint and clearance on the PCB must comply with the antenna specification. The PCB layout shown in the diagram below demonstrates the antenna footprint.



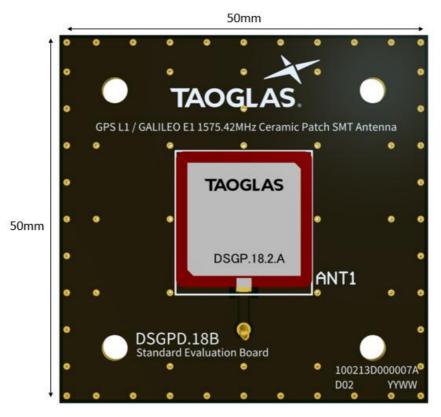
Topside



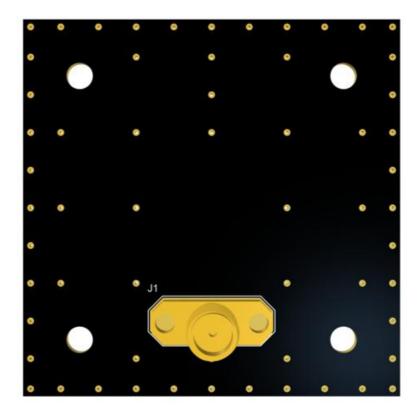
Bottom Side



## 6.4 Evaluation Board



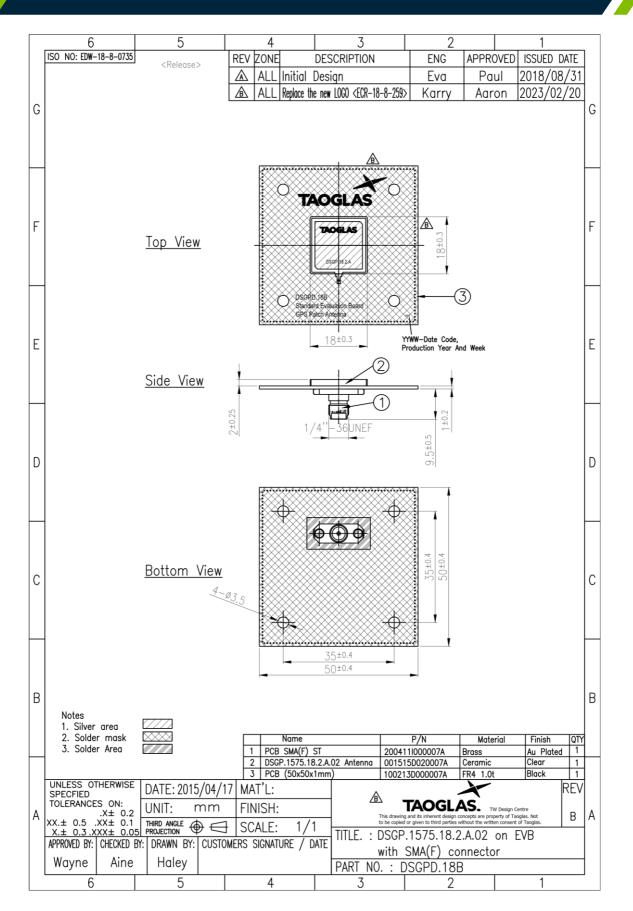
#### Topside



**Bottom Side** 

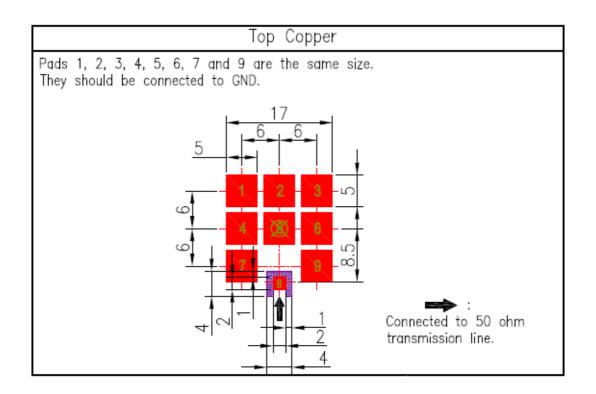


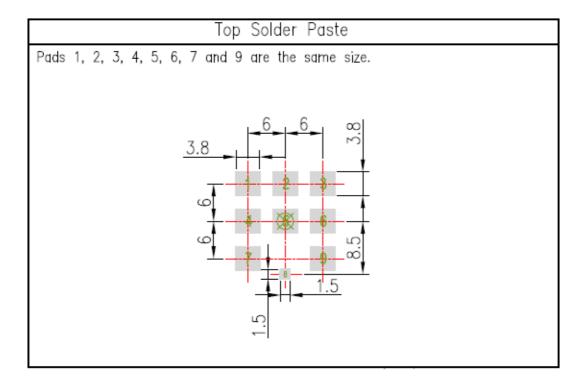
### Evaluation Board Mechanical Drawing



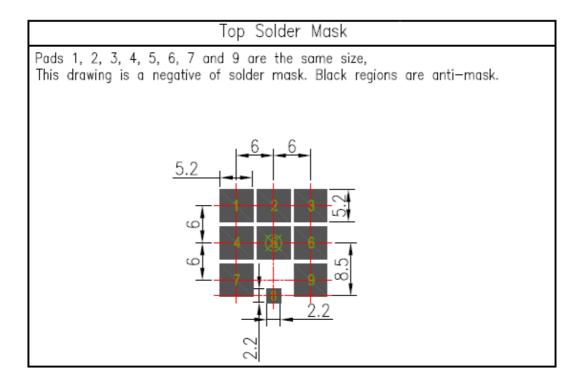


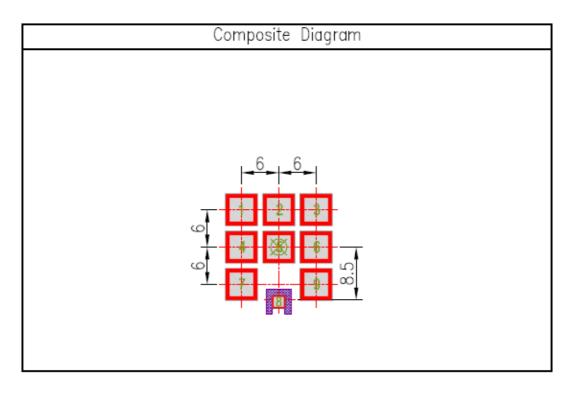
## PCB Footprint Recommendation











NOTE:

- Ag Plated area
  Solder Mask area
  Copper area



- 4. Paste area 5. Copper Keepout Area
- 6. Copper keepout should extend through all PCB layers.

7. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow.

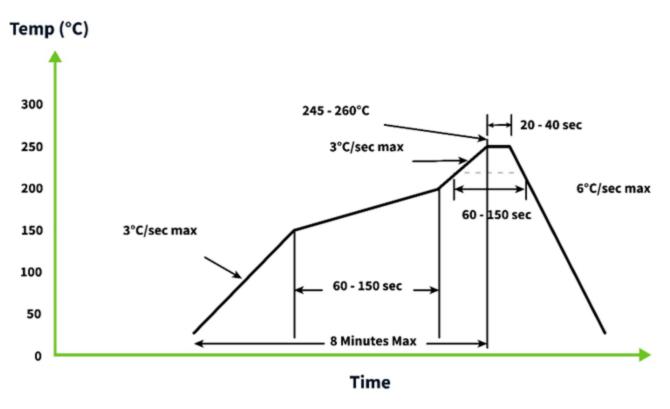
8. The dimension tolerances should follow standard PCB manufacturing guidelines



### Recommended Reflow Soldering Profile

9.

The DSGP.1575.18.2.A.02 can be assembled by following the recommended soldering temperatures are as follows:



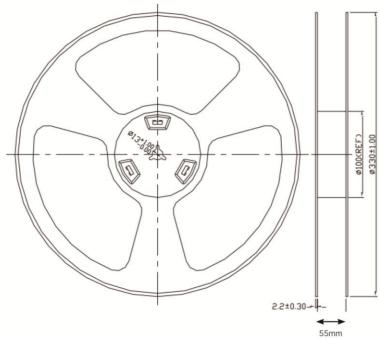
\*Temperatures listed within a tolerance of +/- 10º C

Smaller components are typically mounted on the first pass, however, we do advise mounting the DSGP.1575.18.2.A.02 when placing larger components on the board during subsequent reflows.

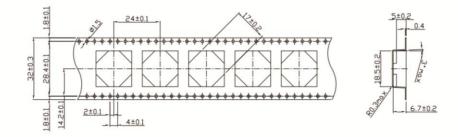


## 10. Packaging

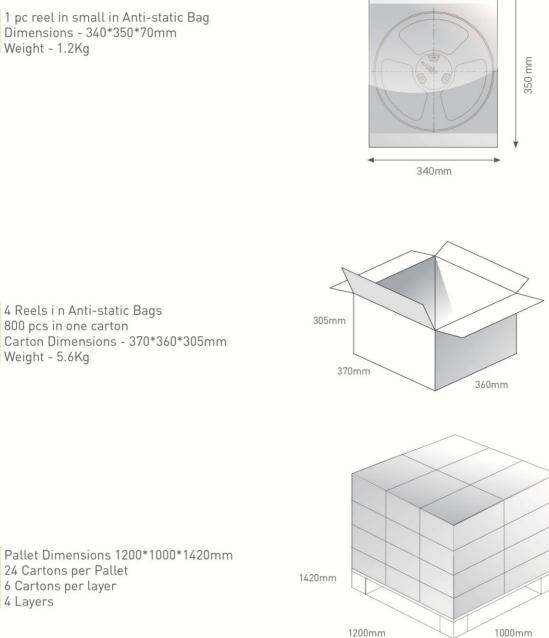
200 pc DSGP.1575.18.2.A.02 per reel Dimensions - Ø330\*55mm Weight - 800g













Changelog for the datasheet

### SPE-17-8-029 - DSGP.1575.18.2.A.02

Date:  2024-10-24    Changes:  Updated Solder Reflow Profile    Changes Made by:  Gary West	Revision: E (Current Version)		
	Date:	2024-10-24	
Changes Made by: Gary West	Changes:	Updated Solder Reflow Profile	
changes made by. Gury West	Changes Made by:	Gary West	

#### **Previous Revisions**

Revision: D		
Date:	2023-02-27	
Changes:	Antenna Integration Guide Added	
Changes Made by:	Cesar Sousa	

Revision: C			
Date:	2021-09-07		
Changes:	Fixed Alignment of radiation patterns section. Added MSL rating. Fixed Font in tables.		
Changes Made by:	Erik Landi		

Revision: B		
Date:	2019-09-17	
Changes:	Updated Drawing	
Changes Made by:	Jack Conroy	

Revision: A (Original First Release)		
Date:	2017-05-22	
Notes:		
Author:	Jack Conroy	



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